NC-AB No Clean Desoldering Wick

June 2012

PRODUCT DESCRIPTION

NC-AB No Clean Desoldering Wick provides the following product characteristics:

Technology	Desoldering Wick
Application	Soldering

NC-AB No Clean Desoldering Wick is designed for static-free desoldering applications and repair of PC boards, without the need for subsequent clean-up. It is formulated using a special halide-free, vacuumised, no-clean, flux-coated copper braid for improved wicking. NC-AB No Clean Desoldering Wick will not loose its efficiency even after prolonged storage in humid conditions. It is made to remain flexible and will not flake.

FEATURES AND BENEFITS

- Faster and increased solder absorption
- Wound-on static dissipative spools
- Negligible residues which are non-corrosive, clear and non-hygroscopic
- Heat stable coating
- Vacuum packed
- Boards using NC-AB No Clean Desoldering Wick will meet the requirements of MIL-P-28809A Cleanliness Test without cleaning

DIRECTIONS FOR USE

Application:

Lay NC-AB No Clean Desoldering Wick over the solder requiring removal and place the soldering iron tip on top of the copper braid. The braid and solder beneath will gradually heat until the solder melts and is absorbed into the braid by capillary action.

Remove the braid, cut off the solder-filled length and dispose the lead contaminated properly.

Sudden heat shock, which may be produced when using a preheated vacuum desoldering tool, is prevented since the braid is cold when it first comes into contact with the joint to be desoldered.

Special Properties

NC-AB No Clean Desoldering Wick is supplied in static dissipative spools conforming to both DOD Standard 1686 and DOC Handbook 263 for static discharge protection. It also meets the decay rate provision of MIL-B-81705B.

Specially processed copper braid is coated with a reduced volume of time tested Xersin 2005 halid free synthetic resin making the quantity of residue after use i significantly less than the conventional desoldering wick. Xersin 2005 meets Bellcore TR-TSY 000078 issue 2, ANSI/IPC SF-818 and is rated IPC-LR3CN.

PCBs desoldered with NC-AB No Clean Desoldering Wick will pass the MIL-P-28809A Cleanliness Test without cleaning, provided a No Clean Flux and a clean system and components are used. PCBs will also pass this test if they have been cleaned after the soldering operation, provided they have been reworked using a No Clean flux in a clean environment.

PACKAGING

NC-AB No Clean Desoldering Wick is supplied in static dissipative plastic spools of 1.5m (5 ft.) each.This provides convenient application and protects the user from heat.

NC-AB No Clean Desoldering Wick is packed in cartons containing five vacuum packed sleeves, each sleeve containing ten static dissipative spools, for a total of fifty spools per carton.

NC-AB No Clean Desoldering Wick is also available in 100 feet Econo-spools.

Approximate Width	Label Color Code
1.88mm (0.074 in) ± 10%	Green

DATA RANGES

The data contained herein may be reported as a typical value and/or a range. Values are based on actual test data and are verified on a periodic basis.

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Fume Hazards and Precautions

The fumes resulting from use may irritate the nose and respiratory organs.Avoid excessive inhaltion.Suitable fume extraction equipment should be used to extract fumes away from the operators.When used at normal soldering temperatures, the amount of lead fume given off is negligible.

Not for Product Specifications
The technical information contained herein is intended for reference only. Please contact Henkel Technologies Technical Service for assistance and recommendations on specifications for this product.

Conversions
(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
µm / 25.4 = mil
N x 0.225 = lb
N/mm x 5.71 = lb/in
N/mm² x 145 = psi
MPa x 145 = psi
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP

Note
The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation and its affiliates ("Henkel") specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel products. Henkel specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage
All trademarks in this document are trademarks and/or registered trademarks of Henkel in the US and elsewhere.

Reference 0.0